

Examiner's G.P.

AN 129:305269 HCA  
TI Tin solder alloys  
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PA Fuji Electric Co., Ltd., Japan  
SO Ger. Offen., 14 pp.  
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DT Patent

LA German

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	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	DE 19816671	A1	19981022	DE 1998-19816671	19980415
	JP 10286689	A2	19981027	JP 1997-97828	19970416
	JP 11058066	A2	19990302	JP 1997-212969	19970807
	JP 11077366	A2	19990323	JP 1998-169937	19980617

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AB The alloys contain >0-3.5 Sb, .1 to req. 3.0% **Ag**, and 1st and 2nd additives for improving the soldering properties. The 1st additives comprise **Cu** >0-1.0 and **Ni** >0-1.0%, and the 2nd additives comprise **P** >0-1.0 and **Ge** >0-1.0%. The alloys contain **Ag** >0-4.0, **Cu** >0-2.0, **Ni** >0-1.0, and **P** >0-1.0 and/or **Ge** >0-1.0%.